PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data		
1.1 Company STMicroelectronics International N.V		STMicroelectronics International N.V
1.2 PCN No.		MDG/22/13736
1.3 Title of PCN		SAMSUNG Foundry (South Korea) additional source for STM32H7Ax & STM32H7Bx 2MB listed products
1.4 Product Category		STM32H7Ax, STM32H7Bx
1.5 Issue date		2022-11-24

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	NEMETH KRISZTINA	
2.1.2 Phone	+49 89460062210	
2.1.3 Email	krisztina.nemeth@st.com	
2.2 Change responsibility		
2.2.1 Product Manager	Ricardo Antonio DE SA EARP	
2.1.2 Marketing Manager	Veronique BARLATIER	
2.1.3 Quality Manager	Pascal NARCHE	

3. Change		
3.1 Category	3.2 Type of change	3.3 Manufacturing Location
	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	ST Crolles (France) SAMSUNG Foundry (South Korea)

4. Description of change		
	Old	New
4.1 Description	Front-end source: - ST Crolles 12" France	Front-end sources: - ST Crolles 12" (France) - SAMSUNG Foundry 12" (South Korea) - added source There is no change in the product functionality. Please refer to PCN 13736 – Additional information attached document.
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	Packaged products : no change.	

5. Reason / motivation for change		
5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose Microcontroller division decided to qualify an additional front-end site to maintain state of the art service leve to our customers thanks to extra capacity.	
5.2 Customer Benefit	CAPACITY INCREASE	

6. Marking of parts / traceability of change	
6.1 Description	Change is visible through diffusion traceability plant, on the marking: - "VQ" for ST Crolles 12" (France) - "LM" for SAMSUNG 12" (South Korea)

7. Timing / schedule		
7.1 Date of qualification results	2023-03-20	
7.2 Intended start of delivery	2023-03-20	
7.3 Qualification sample available?	Upon Request	

8. Qualification / Validation			
8.1 Description 13736 MDG-GPM-RER2203 -PCN13736- eSTM40 tranfser to Samsung Foundry for STM32H7 (die 480) - Reliability Plan.pdf		for STM32H7 (die	
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2022-11-24

9. Attachments (additional documentations)

13736 Public product.pdf 13736 MDG-GPM-RER2203 -PCN13736- eSTM40 tranfser to Samsung Foundry for STM32H7 (die 480) - Reliability Plan.pdf 13736 PCN13736_Additional information.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H7A3NIH6	
	STM32H7A3ZGT6	
	STM32H7A3ZIT6	
	STM32H7B3RIT6	

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